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 Perkins Coie LLP and Affiliates

[FAXCOVER.01]

Attorney Docket No. 10829-8404

**PATENT****IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

IN RE APPLICATION OF: VISHNU K. AGARWAL AND  
DINESH CHOPRA  
APPLICATION No.: 10/772,541  
FILED: FEBRUARY 5, 2004  
FOR: APPARATUSES FOR FORMING A  
PLANARIZING PAD FOR  
PLANARIZATION OF  
MICROELECTRONIC SUBSTRATES

EXAMINER: YEWEBDAR T.  
TADESSE  
ART UNIT: 1734  
CONF. NO: 8900

**Proposed Claim Amendment -**  
**For Discussion Purposes Only**

**Amendment to the Claims:**

75. (Currently Amended) An apparatus for forming a planarizing pad for mechanically and/or chemically-mechanically planarizing a microelectronic substrate, the planarizing pad including a pad support material and a planarizing pad material, wherein the apparatus comprising:

a support device configured to support the pad support material in a selected position;

a vessel for mixing the planarizing pad material; and

a nozzle in fluid communication with the vessel and configured to form the planarizing pad material into discrete texture elements for disposing on the pad support material, wherein the pad support material is elongated in a longitudinal direction, and wherein the nozzle is positioned to spray the discrete texture elements at least partially in the longitudinal direction.

(616) 855 1521

**Remarks**

The foregoing claim amendments are provided for discussion purposes only in a telephone interview scheduled for \_\_\_\_\_ p.m. Eastern time between the Examiner and the attorney identified below.

Respectfully submitted,  
Perkins Coie LLP

Date: \_\_\_\_\_

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Registration No. 51,945

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